6-21-2020

# Hsu, Tai-Ran

San Jose State University

# Attachment No. 1

# Research and Textbooks Authored or Co-authored by Tai-Ran Hsu (1986-2018)


**Book Titles:**

Top row (from left)

1. **The Finite Element Method in Thermomechanics** (391 pp)
   e-book available at springer.com (http://www.springer.com?gp/book/9789401/60001 (ISBN 978-94-011-5998-2) (5-star review @ Amazon.com)
2. **Advanced Machine Design by Microcomputers** (95 pp)
3. **Computer-Aided Design – an integrated approach** (487 pp)
   (4-star review@Amazon.com)

Middle row (from left)

4. **Advances in Electronic Packaging 1995**. (275 pp)
5. **MEMS & Microsystems, Design and Manufacture** (first edition) (436 pp)
   (2.5 star review @Amazon.com)
6. **MEMS Packaging (**(Available @Amazon.com with no review)

Lower row (from left)

7. **MEMS and Microsystems, Design,manufacture and nanoscale engineering (2nd Edition)** (550 pp) (5-star review @ Amazon.com, **The Best Business & Leadership Book** of 2018 by Amazon.com)
8. **Applied Engineering Analysis** (500 pp)(5-star review @ Amazon.com)

## Attachment No. ~~2~~
## Major Research Grants and Contracts/ Awards
## Secured by T.R. Hsu after Joining San Jose State University in 1990

| Projects | Funding Sources | Period | Amount ($) |
|---|---|---|---|
| Wind Power Generation on High Rise Buildings in Urban Centers<br>Co-PIs: Craig Clements & Eugene Cordero<br>(Meteorology Dept., SJSU) | California Energy Commission | Sep/10 to Dec/11 | 50000 |
| A Mobile Atmospheric Profiling System for Multi-Campus Research & Education (CSU-MAPS). PI: Craig Clements<br>(Meteorology Dept., SJSU)<br>Co-PIs: T.R. Hsu and A. Bridger | National Science Foundation<br>MRI-R² (Major Research Instrumentation Program) | Jul/09 to Dec/12 | 446894 |
| Hybrid Powered Zero Emission (ZEM) Vehicle Design and Development<br>(a student project) | College of Engineering, SJSU | Jul/07 to Jun/08 | 41000 |
| | | Jul/06 to Jun/07 | 36229 |
| Laboratory Experiments in MEMS<br>PI: John Lee, CO-PIs: T.R. Hsu, G. Stacy and D. Parent | National Science Foundation<br>Washington, DC | Aug/04 to Jul/06 | 115564 |
| Laboratory and Curriculum Development in Thermal Management of Electronics<br>PI: Nicole Okamoto, CO-PI: T.R. Hsu | National Science Foundation<br>Washington, DC | Jul/03 to Jun/06 | 105757 |
| On Miniature Microphone Design | Industrial Technology Research Institute, San Jose, CA | | 45000 |
| On Moisture-Induced Fracture of Integrated Circuits with Plastic Encapsu-lations | US Airforce/National Semicon-ductor Corp., Santa Clara, CA | Jun/95 to Jul/96 | 63000 |
| Undergraduate Curriculum Development on Mechatronics Systems Engineering | National Science Foundation<br>Washington, DC | Feb/95 to Jan/98 | 494279 |
| | Hewlett-Packard Company | | 70978 |
| | David Brown Fellowship in mechatronics | | 50000 |
| Trans-Pacific Workshops on Mechatronic Technology | National Science Foundation<br>Washington, DC | Jan/95 to Dec/96 | 50000 |
| Planning Trip on Trans-Pacific Workshops on Mechatronic Technology | National Science Foundation<br>Washington, DC | Jan-94 | 8200 |
| Fatigue Strength of Adhesives for Wind Turbine blades | FloWind Corporation<br>Pleasanton, CA | Jan/92 to Dec/93 | 27000 |
| | | **Total:** | **$1,603,901** |